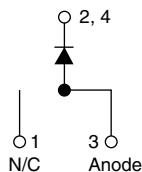


# Hyperfast Rectifier, 8 A FRED Pt®



## FEATURES

- Hyper fast recovery time, reduced  $Q_{rr}$  and soft recovery
- 175 °C maximum operating junction temperature
- For PFC CRM/CCM operation
- Low forward voltage drop
- Low leakage current
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8 A
$V_R$	600 V
$V_F$ at $I_F$	1.3 V
$t_{rr}$ (typ.)	18 ns
$T_J$ max.	175 °C
Package	DPAK (TO-252AA)
Circuit configuration	Single

## DESCRIPTION / APPLICATIONS

State of the art hyper fast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery. The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 143\text{ °C}$	8	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$	90	
Peak repetitive forward current	$I_{FM}$	$T_C = 143\text{ °C}$ , $f = 20\text{ kHz}$ , $d = 50\%$	16	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	$V_F$	$I_F = 8\text{ A}$	-	2.0	2.4	
		$I_F = 8\text{ A}$ , $T_J = 150\text{ °C}$	-	1.3	1.8	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	50	$\mu\text{A}$
		$T_J = 150\text{ °C}$ , $V_R = V_R$ rated	-	-	500	
Junction capacitance	$C_T$	$V_R = 600\text{ V}$	-	8	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8	-	nH



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$		21		ns
		$I_F = 1\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	18	22	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	25	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	34	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	3.3	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	4.8	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	39	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	90	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case per leg	$R_{thJC}$		-	1.8	2.2	$^{\circ}\text{C}/\text{W}$
Approximate weight			0.3			g
			0.01			oz.
Marking device		Case style DPAK (TO-252AA)	8EWH06FNH			

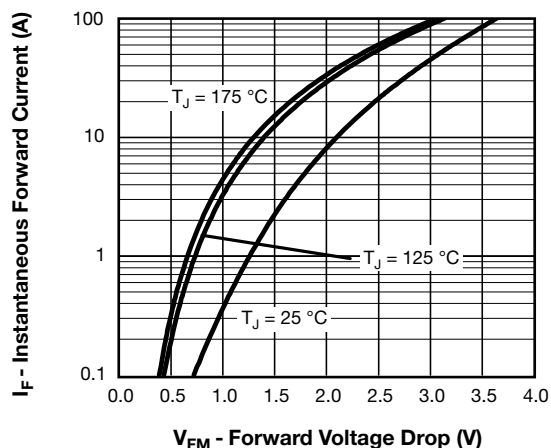


Fig. 1 - Typical Forward Voltage Drop Characteristics

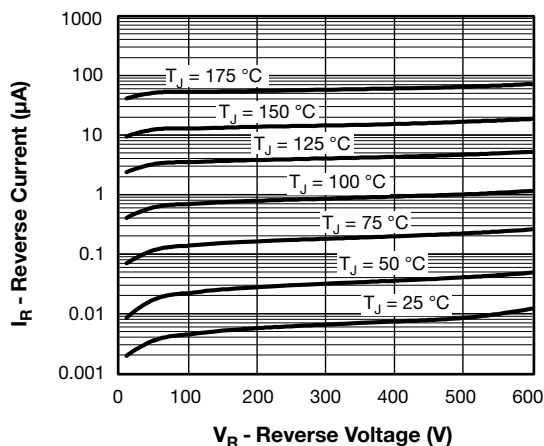


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

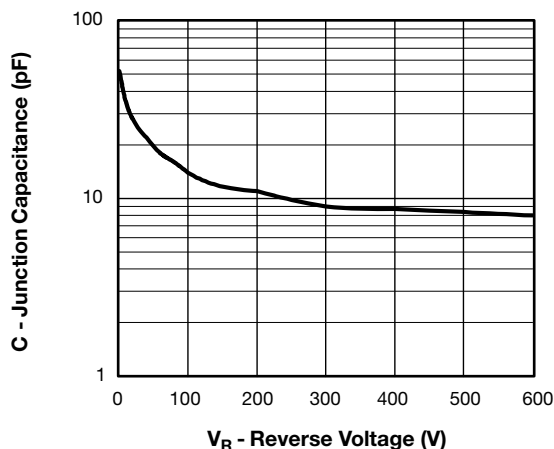
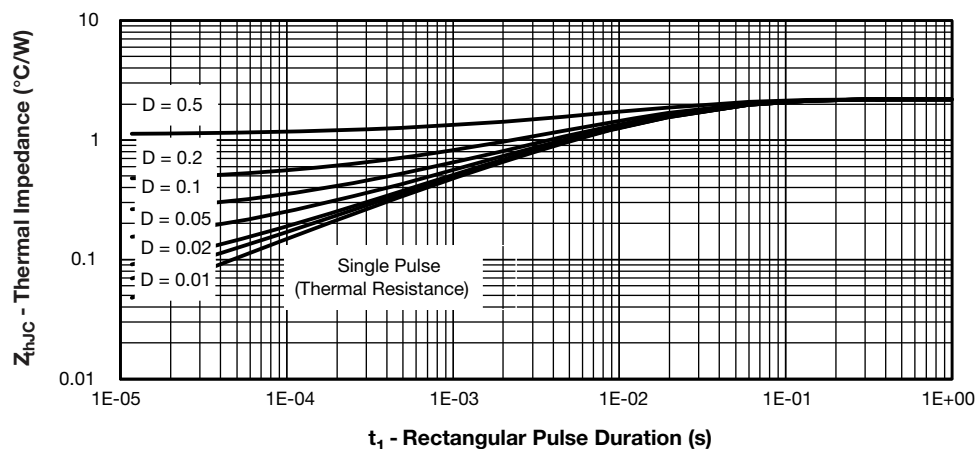


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

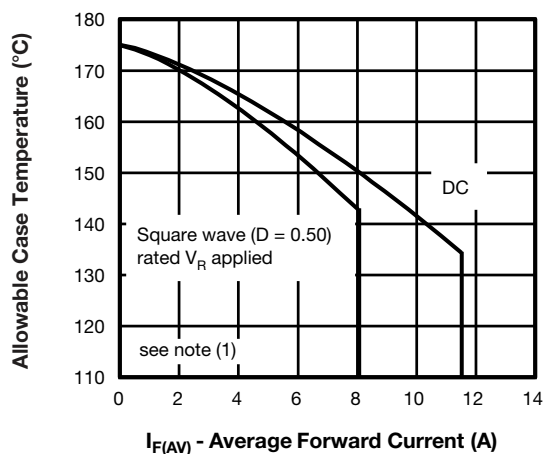


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

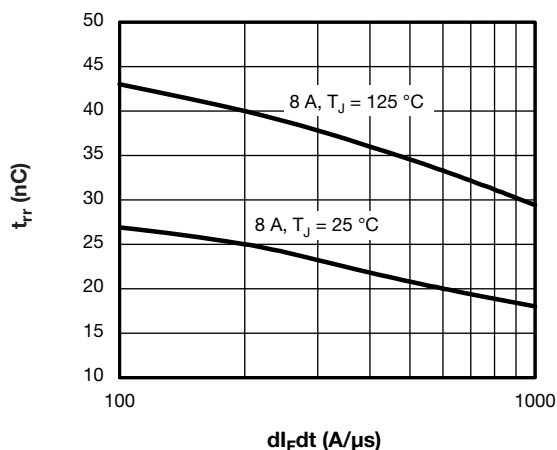


Fig. 7 - Typical Reverse Recovery Time vs.  $dI_F/dt$

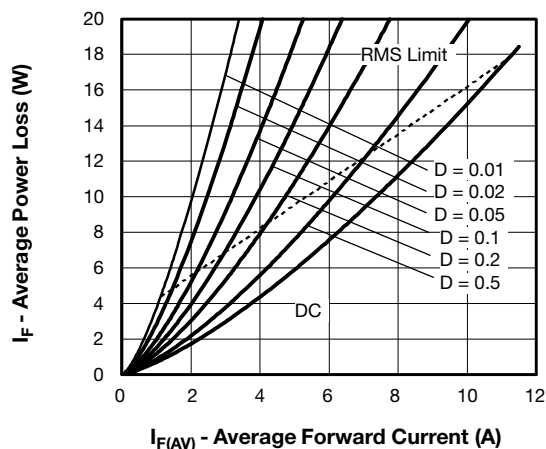


Fig. 6 - Forward Power Loss Characteristics

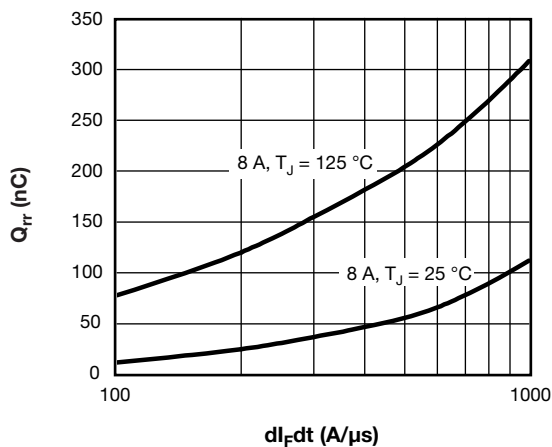


Fig. 8 - Typical Stored Charge vs.  $dI_F/dt$

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = Rated  $V_R$

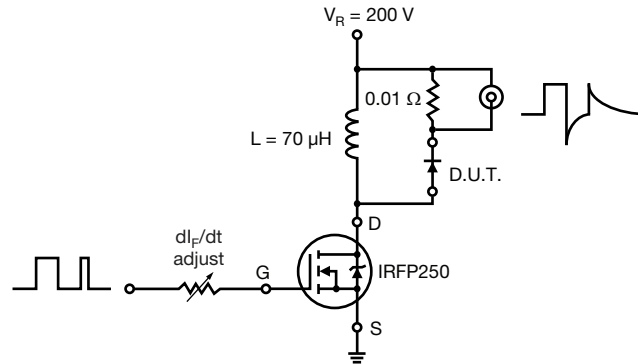


Fig. 9 - Reverse Recovery Parameter Test Circuit

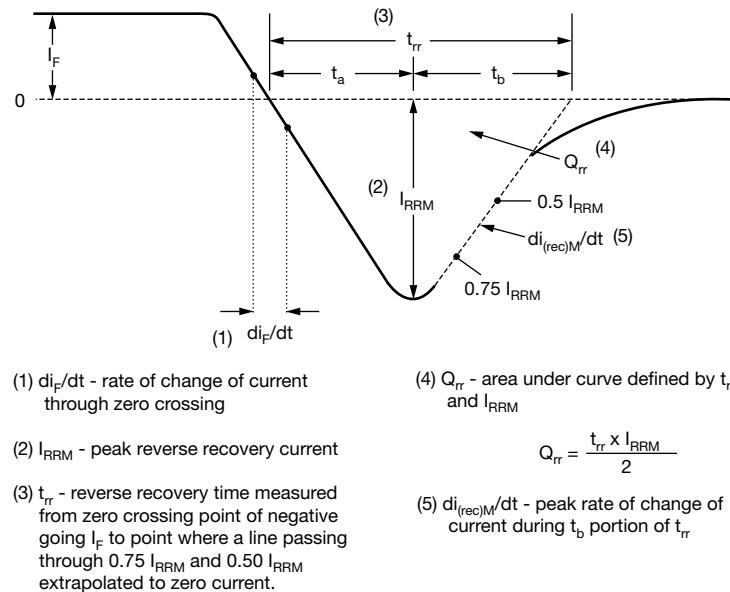


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

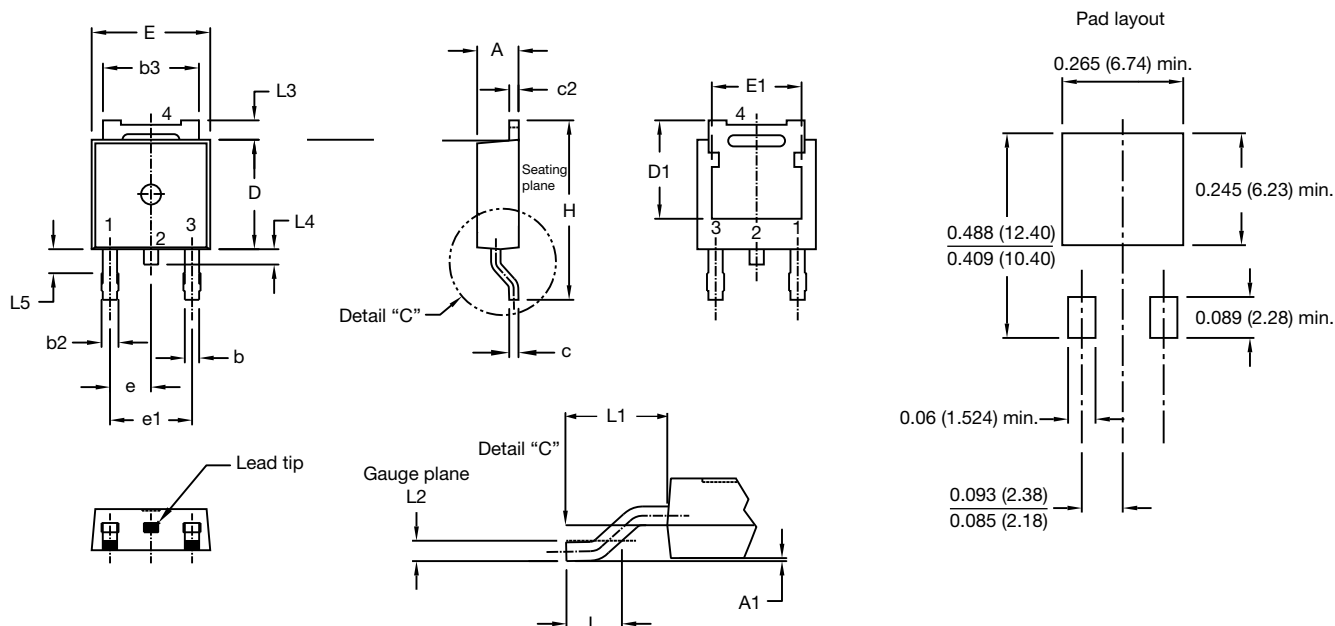
Device code	VS-	8	E	W	H	06	FN	TRL	H	M3
	1	2	3	4	5	6	7	8	9	10
<b>1</b>	- Vishay Semiconductors product									
<b>2</b>	- Current rating (8 = 8 A)									
<b>3</b>	- Circuit configuration: E = single diode									
<b>4</b>	- Package identifier: W = D-PAK									
<b>5</b>	- H = hyperfast recovery									
<b>6</b>	- Voltage rating (06 = 600 V)									
<b>7</b>	- FN = TO-252AA									
<b>8</b>	- <ul style="list-style-type: none"><li>• None = tube</li><li>• TR = tape and reel</li><li>• TRL = tape and reel (left oriented)</li><li>• TRR = tape and reel (right oriented)</li></ul>									
<b>9</b>	- H = AEC-Q101 qualified									
<b>10</b>	- Environmental digit: M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free									

<b>ORDERING INFORMATION</b> (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-8EWH06FNHM3	75	Antistatic plastic tube
VS-8EWH06FNTRHM3	2000	13" diameter reel
VS-8EWH06FNTRRH3	3000	13" diameter reel
VS-8EWH06FNTRLHM3	3000	13" diameter reel

<b>LINKS TO RELATED DOCUMENTS</b>	
Dimensions	<a href="http://www.vishay.com/doc?95519">www.vishay.com/doc?95519</a>
Part marking information	<a href="http://www.vishay.com/doc?95518">www.vishay.com/doc?95518</a>
Packaging information	<a href="http://www.vishay.com/doc?95033">www.vishay.com/doc?95033</a>
SPICE model	<a href="http://www.vishay.com/doc?96114">www.vishay.com/doc?96114</a>

### DPAK (TO-252AA)

#### DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	4.93	-	0.194	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension



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